Boeing Access to Education Scholarship

Six scholarships for $1,000 each will be awarded to incoming and current skilled trade students enrolled at Helena College University of Montana. Scholarship will be applied to the Fall 2024 semester. Preference will be given to students enrolled in the Aviation Maintenance Technology, CNC Machining or Machine Tool Technology programs. Eligible programs include:

- Automotive Technology
- Aviation Maintenance Technology
- CNC Machining
- Computer Technology
- Diesel Technology
- Metals Technology
- Machine Tool Technology
- Welding Technology

Selection Criteria:
1. Status as an underrepresented or economically disadvantaged student determined by the Free Application for Federal Student Aid (FAFSA).
2. Enrollment at Helena College in one of the above trade programs.
3. Must have and/or maintain a cumulative GPA of 3.0 or higher and demonstrate excellent leadership and communication skills.
4. Expressed interest in aerospace or cyber security careers.

Application Process:
Please include:
- This application coversheet,
- A typed personal essay,
  - The essay should include an explanation of your career goals, work experience, work ethic, attendance, grades and out of school activities (i.e., community service).
- An instructor evaluation form (attached),
  - Please have your instructor place their evaluation form in a sealed envelope to enclose with your application packet.
- A letter of recommendation from a current/previous employer or a community member.

Submit these forms to the Financial Aid Office at Helena College, 1115 North Roberts Street, Helena, MT 59601 by 5pm on March 29th, 2024.

Scholarship winners will be encouraged to participate in summer internship opportunities offered by Boeing. Scheduled events for the spring in which scholarship recipients are expected to participate will include a "Careers in Aerospace" event and a "Scholars Dinner" with local/regional Boeing representatives.
Personal Information (PRINT)

Name____________________________________________ Date___________
Mailing Address___________________________________ City___________
State______________________ Zip Code______________ GPA ____________
Program of Study__________________________________________________
Intended Graduation Date__________________________________________

The scholarship committee/Helena College may submit a notice of the award to the local newspaper or use the award information in public relations documents. The award information may include your name, program, and dollar amount awarded. By signing this form, you acknowledge and agree that this information may be disclosed.

Signature_________________________________________________________________________________________
BOEING ACCESS TO EDUCATION SCHOLARSHIP
INSTRUCTOR EVALUATION FORM
CONFIDENTIAL REPORT (MUST BE SUBMITTED IN A SEALED ENVELOPE)

Name of Applicant ____________________________________________________________

Rank this student academically: (circle one)
Top 25 percent of class  Middle 50 percent of class  Bottom 25 percent of class

Please indicate your rating of this applicant by circling the appropriate letter and providing comments:

**EXCELLENT (E)  GOOD (G)  FAIR (F)  POOR (P) **

1. Scholastic Achievement  
E  G  F  P
________________________________________________________
________________________________________________

2. Character and Personality  
E  G  F  P
___________________________________________________
______________________________________________________

3. Leadership  
E  G  F  P
___________________________________________________
______________________________________________________

4. Initiative  
E  G  F  P
___________________________________________________
______________________________________________________

5. Dependability  
E  G  F  P
___________________________________________________
______________________________________________________

6. Work Ethic  
E  G  F  P
___________________________________________________
______________________________________________________

Additional Comments
___________________________________________________
______________________________________________________

Print Name ________________________________________________________________

Signature __________________________ Date ___________________

**This form must be submitted in a sealed envelope**